ABSTRACT OF THE DISCLOSURE

The invention provides a piezoelectric device having a structure which resists impact from the exterior of the device, and stress applied to a piezoelectric resonator element, and which can enhance electrical conductance between an electrode side of a package base and the piezoelectric resonator element, and to provide a manufacturing method therefor. A piezoelectric device having a structure in which a piezoelectric resonator element is bonded to electrodes provided on a package base, includes mounting electrodes, which are provided on the package base, to which a driving voltage is carried, via conduction paths, and on which the piezoelectric resonator element is mounted; and anchor members, which are disposed on the surfaces of the mounting electrodes, and which are formed of a material having superior adhesion to the surfaces thereof, in which the piezoelectric resonator element is bonded to these conductive anchor members with silicone-based conductive adhesives provided therebetween.